

pillared (columnar) or spherical electrodes which are joined to upper face electrodes of the first semiconductor and the heat radiating plate, respectively.

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On page 13 after line 11, insert the following new paragraph:

Fig. 19 is a schematic cross-sectional view showing connection of a lower face electrode to a heat radiating plate via solder or conductive paste.

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Please replace paragraph [0060] on page 14, with the following rewritten paragraph:

In the semiconductor package according to the first embodiment of the present invention, as schematically shown in Fig. 19, a lower face electrode 50 of a semiconductor 1, having electrodes formed on both upper and lower faces, is joined to a heat radiating plate 10 with use of solder 51. Upper face electrodes 2 and 3 of the semiconductor 1, and the radiating plate 10, are joined to pillared (columnar) or spherical electrodes 11.

Please replace the Abstract of the Disclosure paragraph with the following rewritten paragraph:

6.1
Electrodes of one face of a semiconductor, which has electrodes formed on both faces, and a heat radiating plate are directly joined to quickly absorb and diffuse heat of the semiconductor, thereby improving a heat radiation effect. At the same time, electrodes on an opposite face of the semiconductor are connected to pillared electrodes that are thicker than a wire for wire bonding and larger in current capacity. These pillared electrodes can accordingly be utilized as connecting terminals to a circuit board. Ceramic is used for the heat radiating plate, so that semiconductors of different functions can be mounted simultaneously.